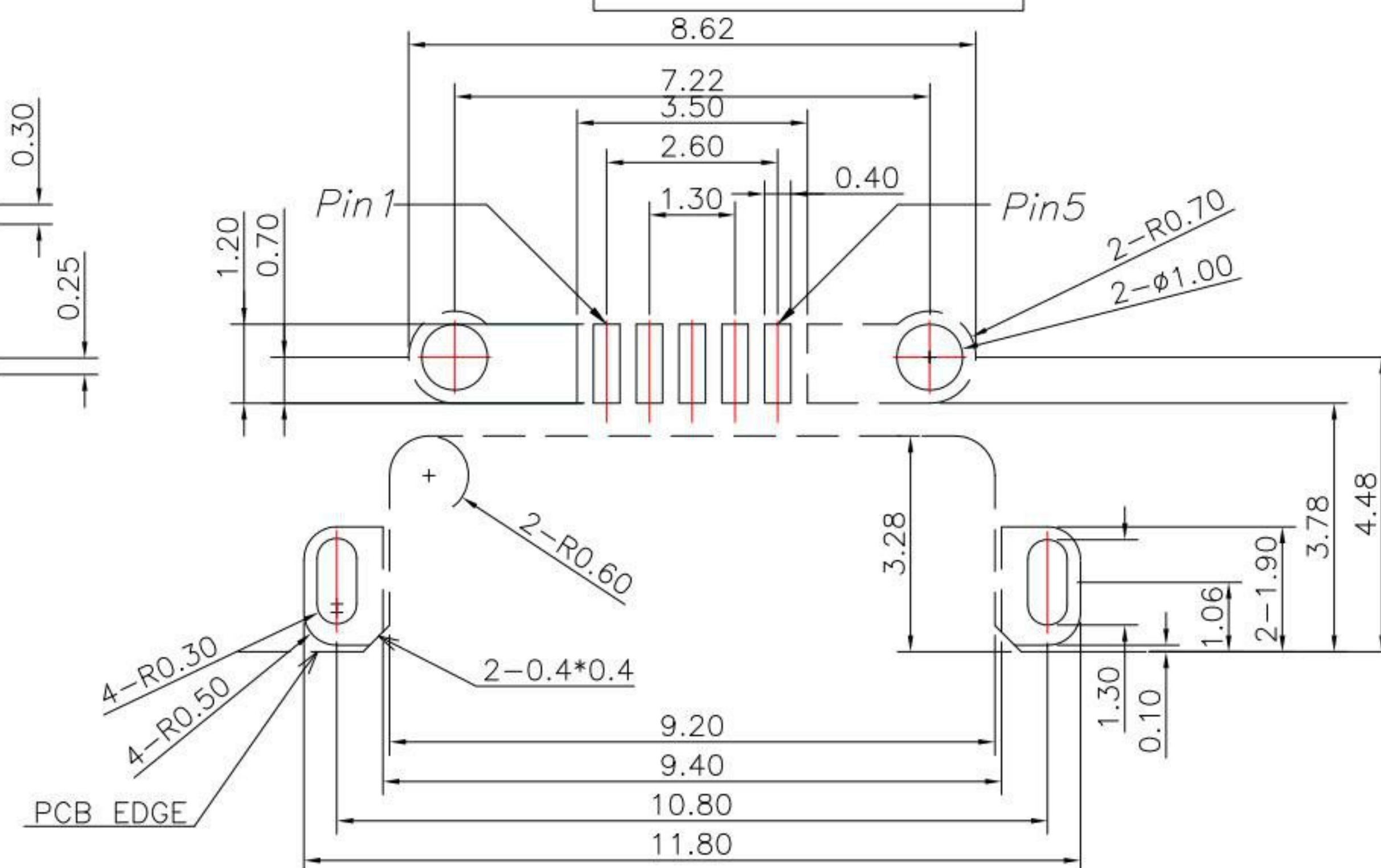
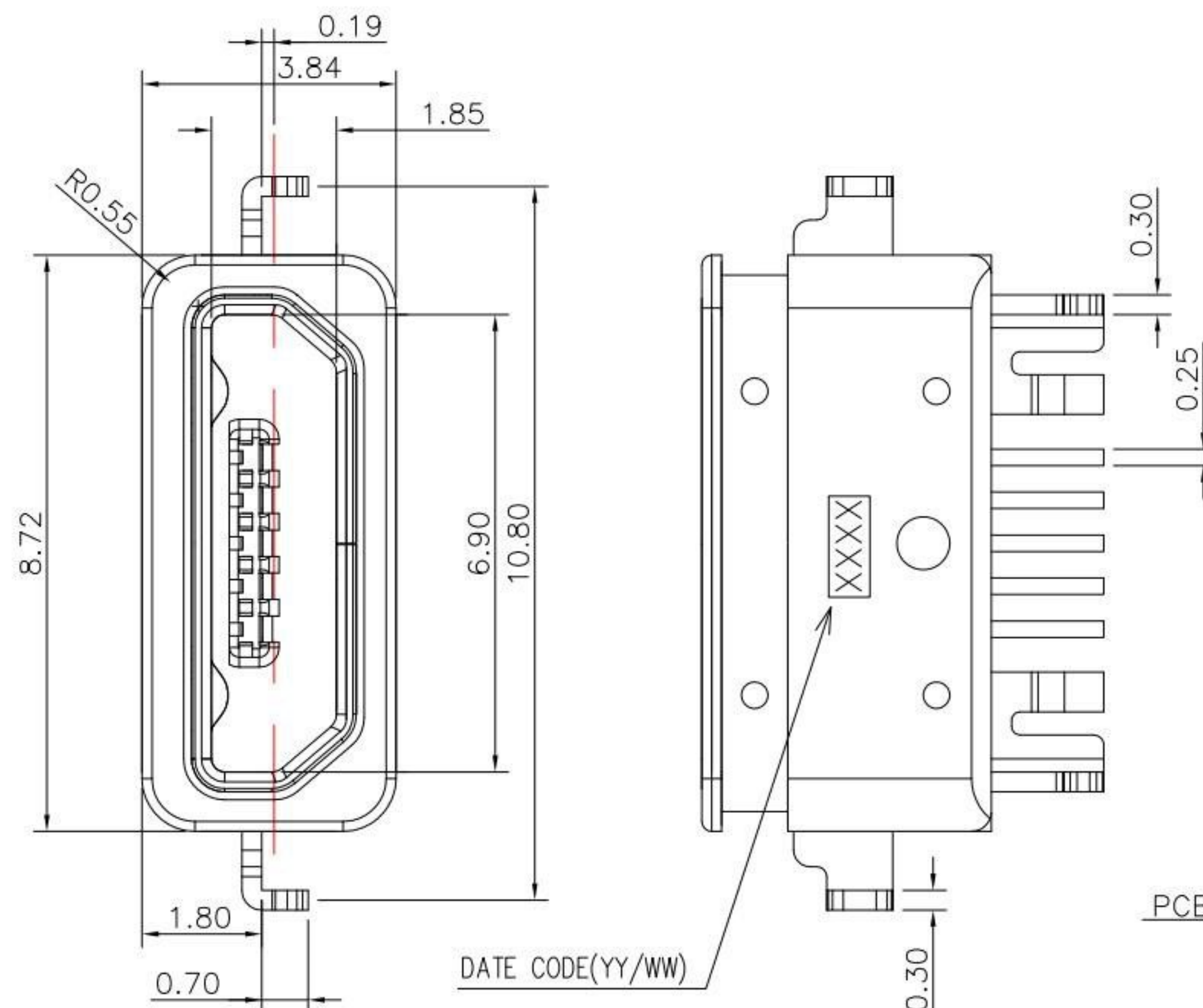
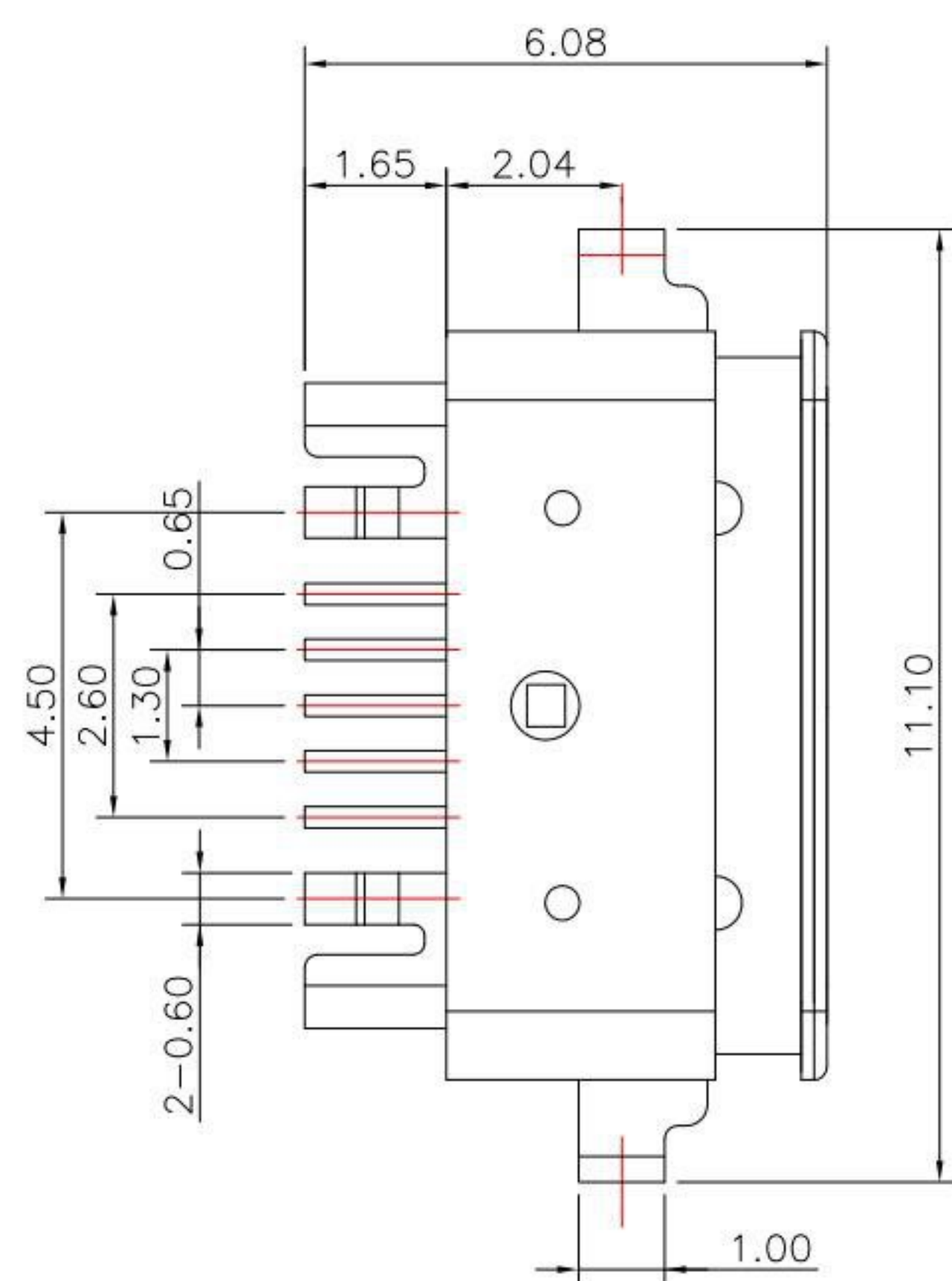
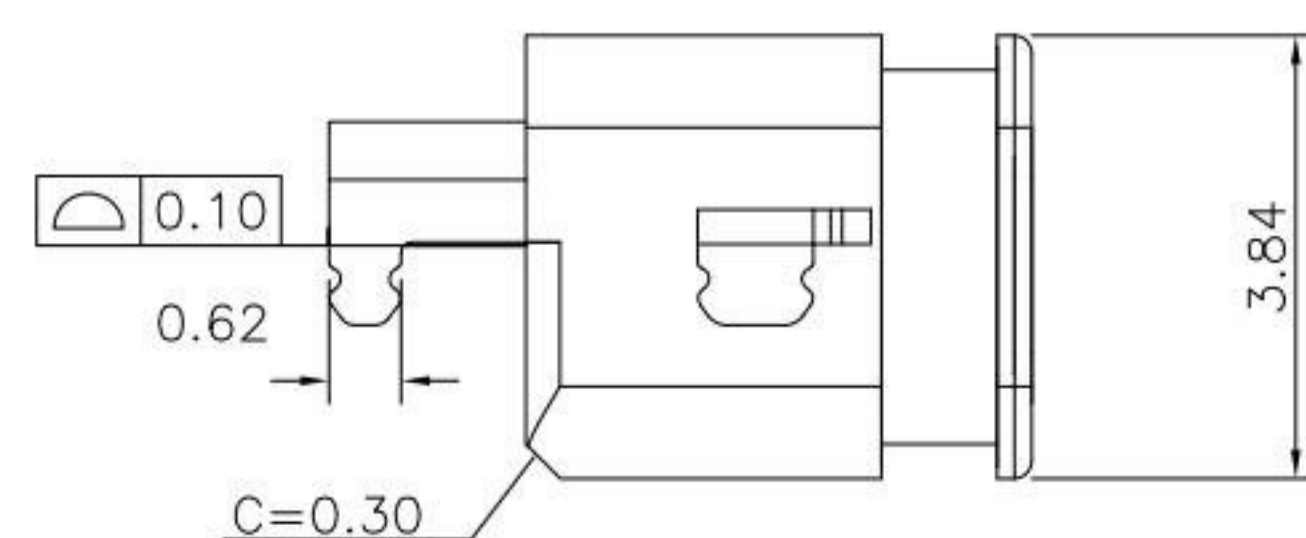


IP67



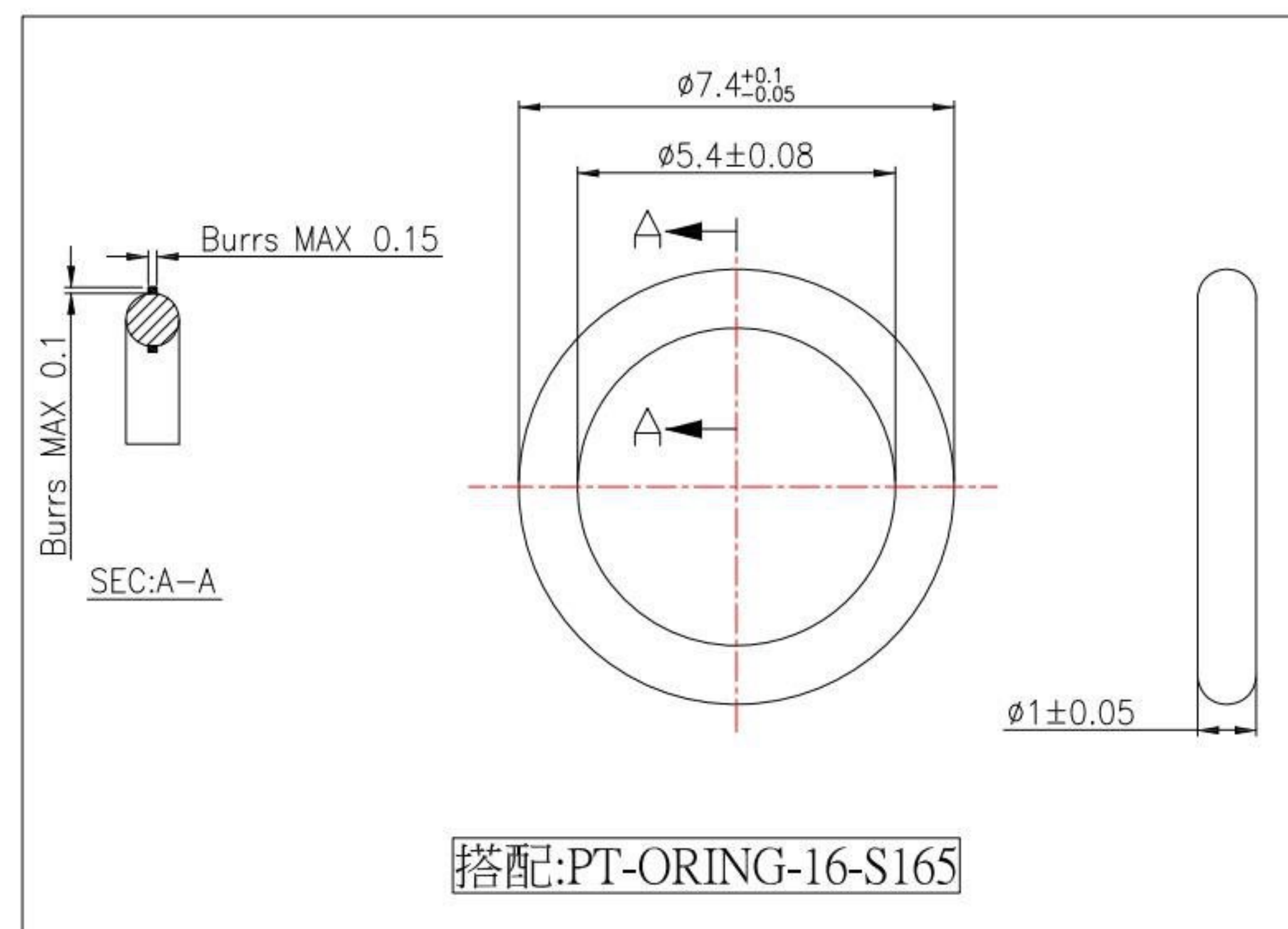
P.C.B LAYOUT MOUNTING PATTERN



MRUSB-5B-WP13-x-S165

鍍層厚度:

Blank	: 1u"
2	: 15u"
3	: 30u"



搭配:PT-ORING-16-S165

NOTES:

MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC
- 1.2 CONTACT: COPPER ALLOY
- 1.3 SHELL: SUS
- 1.4 O-RING: SILICON

FINISH:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

3.SPECIFICATION:

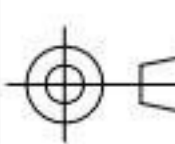
- 3.1 RATING: 1.0A
- 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 500 VAC
- 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 1000 MΩ MIN.

5	新增O-RING圖	Jack	102920
5	刪除O-RING圖	Jack	040819
4	更新樣式	Jack	032119
3	新增O-RING圖	Jack	112618
2	新增尺寸	Jack	073118
1	更新為A0版	Jack	071718
ITEM NO.	DESCRIPTION	DRAWN	DATE

KSD 科斯达电子科技有限公司
SWITCH CONNECTOR KSD ELECTRONIC TECHNOLOGY Co., LTD
全球 互聯零組件製造企業

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE
Jack Lu	10/29/20
CHECKED BY:	DATE
Jacky Chen	10/29/20
APPROVED BY:	DATE
Tony Kao	10/29/20

MAT'L	TITLE	CONNECTOR
FINISH	MODLE	MICRO USB 5PF B TYPE 沉板 板上 H 1.8 IP67
SCALE 1:1	DWG NO.	MRUSB-5B-WP13-x-S165
SHEET NO. 1 of 1	PART NO.	MRUSB-5B-WP13-x-S165
	SIZE	A4
	VER	R6